

Advanced Power MOSFET

IRLM220A

FEATURES

- ✓ Avalanche Rugged Technology
- ✓ Rugged Gate Oxide Technology
- ✓ Lower Input Capacitance
- ✓ Improved Gate Charge
- ✓ Extended Safe Operating Area
- ✓ Lower Leakage Current : 10 μ A (Max.) @ $V_{DS} = 200V$
- ✓ Lower $R_{DS(ON)}$: 0.609 Ω (Typ.)

$BV_{DSS} = 200 V$

$R_{DS(on)} = 0.8 \Omega$

$I_D = 1.13 A$

SOT-223



1. Gate 2. Drain 3. Source

Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V_{DSS}	Drain-to-Source Voltage	200	V
I_D	Continuous Drain Current ($T_A=25^\circ C$)	1.13	A
	Continuous Drain Current ($T_A=70^\circ C$)	0.9	
I_{DM}	Drain Current-Pulsed (1)	9	A
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulsed Avalanche Energy (2)	29	mJ
I_{AR}	Avalanche Current (1)	1.13	A
E_{AR}	Repetitive Avalanche Energy (1)	0.2	mJ
dv/dt	Peak Diode Recovery dv/dt (3)	5	V/ns
P_D	Total Power Dissipation ($T_A=25^\circ C$) *	2	W
	Linear Derating Factor *	0.016	$W/^\circ C$
T_J, T_{STG}	Operating Junction and Storage Temperature Range	- 55 to +150	$^\circ C$
T_L	Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5-seconds	300	

Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient *	--	62.5	$^\circ C/W$

* When mounted on the minimum pad size recommended (PCB Mount).

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
BV_{DSS}	Drain-Source Breakdown Voltage	200	--	--	V	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$
$\Delta\text{BV}/\Delta T_J$	Breakdown Voltage Temp. Coeff.	--	0.18	2.0	$\text{V}/^\circ\text{C}$	$\text{I}_D=250\mu\text{A}$ See Fig 7
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	1.0	--	100	V	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=250\mu\text{A}$
I_{GSS}	Gate-Source Leakage , Forward	--	--	-100	nA	$\text{V}_{\text{GS}}=20\text{V}$
	Gate-Source Leakage , Reverse	--	--	10		$\text{V}_{\text{GS}}=-20\text{V}$
I_{DSS}	Drain-to-Source Leakage Current	--	--	100	μA	$\text{V}_{\text{DS}}=200\text{V}$
		--	--			$\text{V}_{\text{DS}}=160\text{V}, \text{T}_C=125^\circ\text{C}$
$\text{R}_{\text{DS(on)}}$	Static Drain-Source On-State Resistance	--	--	0.8	Ω	$\text{V}_{\text{GS}}=5\text{V}, \text{I}_D=0.57\text{A}$ (4)
g_{fs}	Forward Transconductance	--	2.8	--	S	$\text{V}_{\text{DS}}=40\text{V}, \text{I}_D=0.57\text{A}$ (4)
C_{iss}	Input Capacitance	--	330	430	pF	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=25\text{V}, f = 1\text{MHz}$ See Fig 5
C_{oss}	Output Capacitance	--	55	70		
C_{rss}	Reverse Transfer Capacitance	--	8	30		
$t_{\text{d(on)}}$	Turn-On Delay Time	--	6	25	ns	$\text{V}_{\text{DD}}=100\text{V}, \text{I}_D=5\text{A}, \text{R}_G=9\Omega$ See Fig 13 (4)(5)
t_r	Rise Time	--	24	20		
$t_{\text{d(off)}}$	Turn-Off Delay Time	--	6	60		
t_f	Fall Time	--	6	20		
Q_g	Total Gate Charge	--	10.3	15	nC	$\text{V}_{\text{DS}}=160\text{V}, \text{V}_{\text{GS}}=5\text{V}, \text{I}_D=5\text{A}$ See Fig 6 & Fig 12 (4)(5)
Q_{gs}	Gate-Source Charge	--	2.0	--		
Q_{gd}	Gate-Drain ("Miller") Charge	--	4.4	--		

Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
I_S	Continuous Source Current	--	--	1.13	A	Integral reverse pn-diode in the MOSFET
I_{SM}	Pulsed-Source Current (1)	--	--	9		
V_{SD}	Diode Forward Voltage (4)	--	--	1.5	V	$\text{T}_J=25^\circ\text{C}, \text{I}_S=1.13\text{A}, \text{V}_{\text{GS}}=0\text{V}$
t_{rr}	Reverse Recovery Time	--	140	--	ns	$\text{T}_J=25^\circ\text{C}, \text{I}_F=5\text{A}$ $d\text{I}/dt=100\text{A}/\mu\text{s}$ (4)
Q_{rr}	Reverse Recovery Charge	--	0.59	--		

Notes :

- (1) Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- (2) $L=35\text{mH}$, $\text{I}_{\text{AS}}=1.13\text{A}$, $\text{V}_{\text{DD}}=50\text{V}$, $\text{R}_G=27\Omega$, Starting $\text{T}_J=25^\circ\text{C}$
- (3) $\text{I}_{\text{SD}} \leq 5\text{A}$, $d\text{I}/dt \leq 180\text{A}/\mu\text{s}$, $\text{V}_{\text{DD}} \leq \text{BV}_{\text{DSS}}$, Starting $\text{T}_J=25^\circ\text{C}$
- (4) Pulse Test : Pulse Width = $250\mu\text{s}$, Duty Cycle $\leq 2\%$
- (5) Essentially Independent of Operating Temperature

Fig 1. Output Characteristics

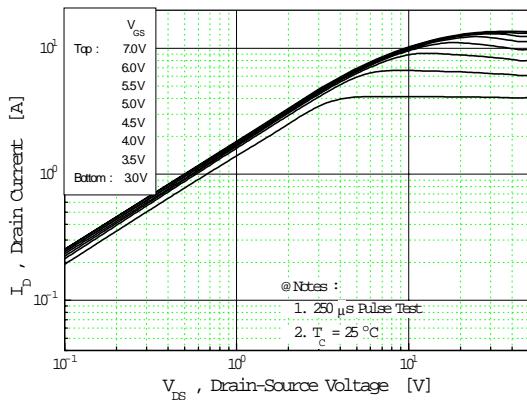


Fig 2. Transfer Characteristics

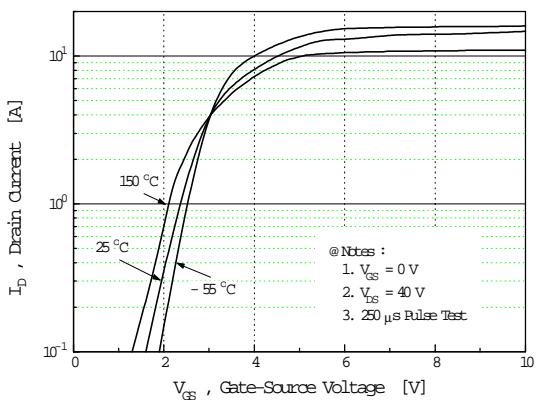


Fig 3. On-Resistance vs. Drain Current

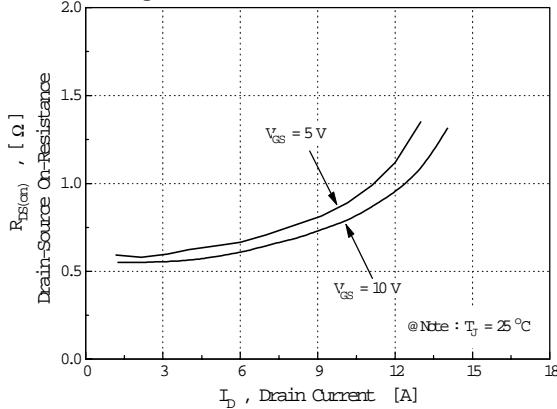


Fig 4. Source-Drain Diode Forward Voltage

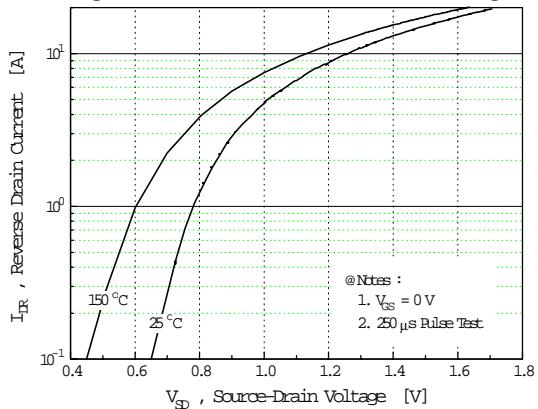


Fig 5. Capacitance vs. Drain-Source Voltage

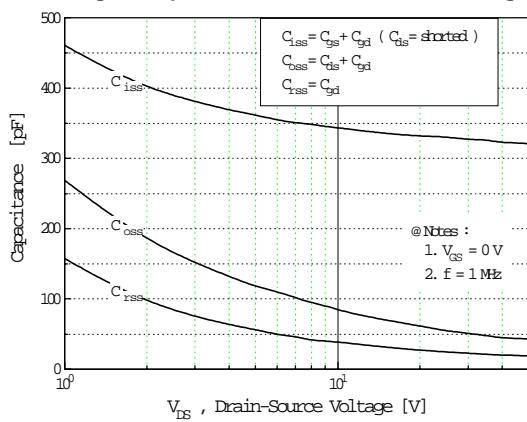
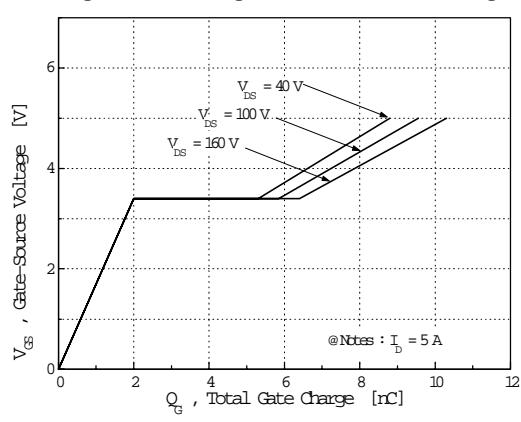


Fig 6. Gate Charge vs. Gate-Source Voltage



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Fig 7. Breakdown Voltage vs. Temperature

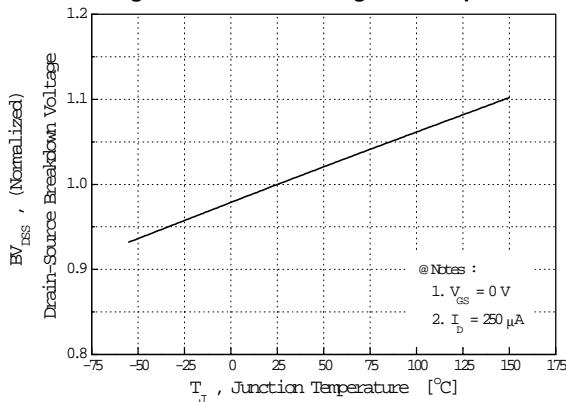


Fig 8. On-Resistance vs. Temperature

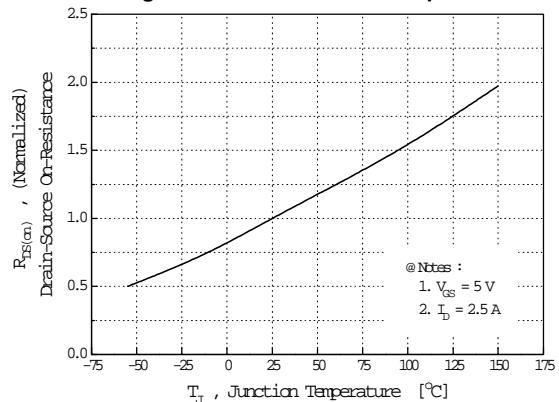


Fig 9. Max. Safe Operating Area

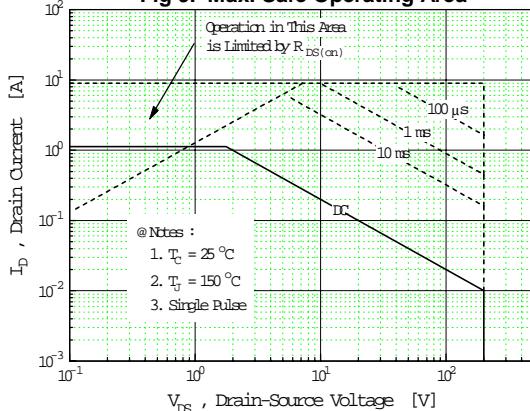


Fig 10. Max. Drain Current vs. Ambient Temperature

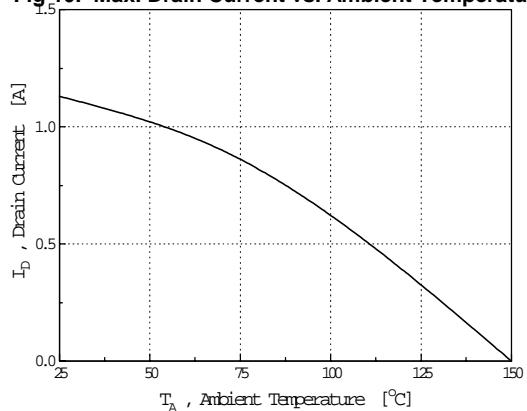
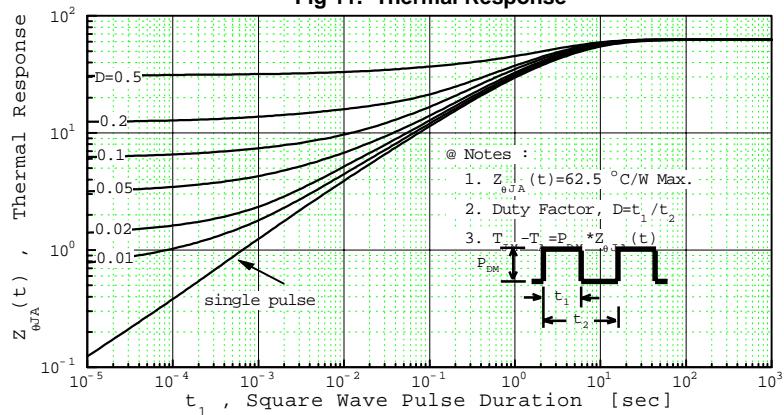


Fig 11. Thermal Response



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Fig 12. Gate Charge Test Circuit & Waveform

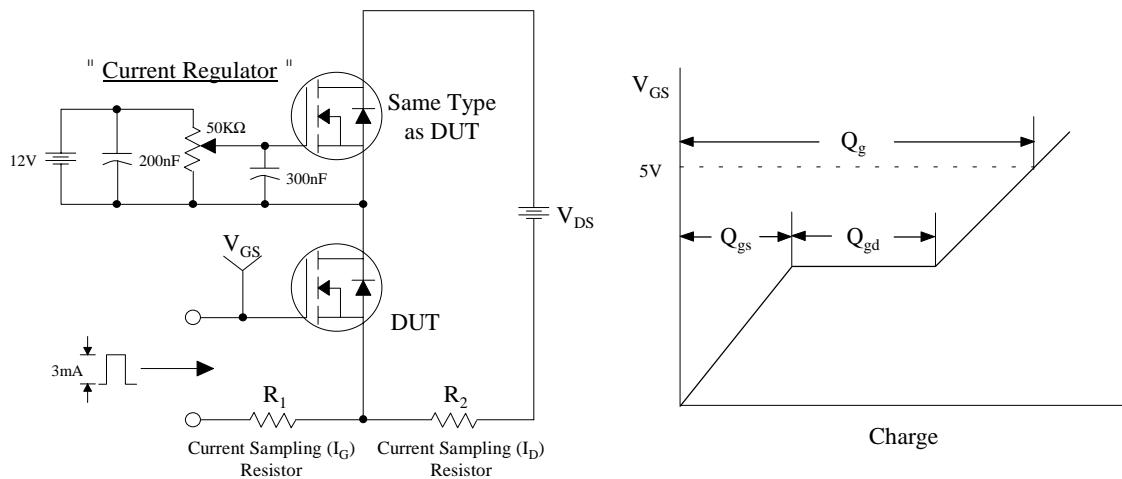


Fig 13. Resistive Switching Test Circuit & Waveforms

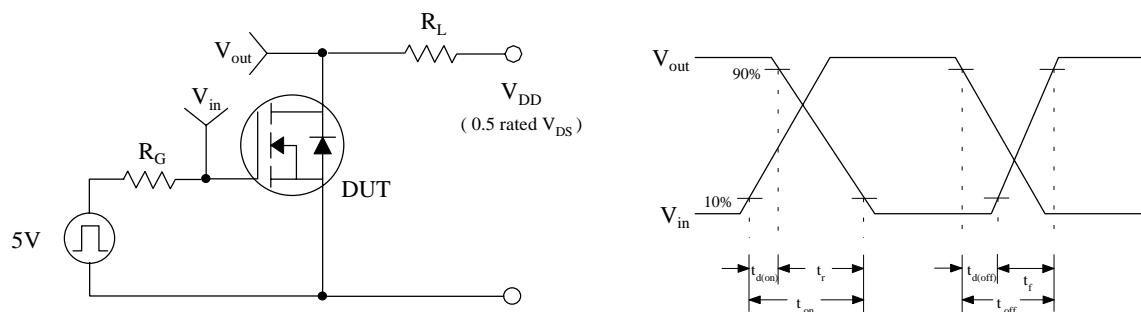
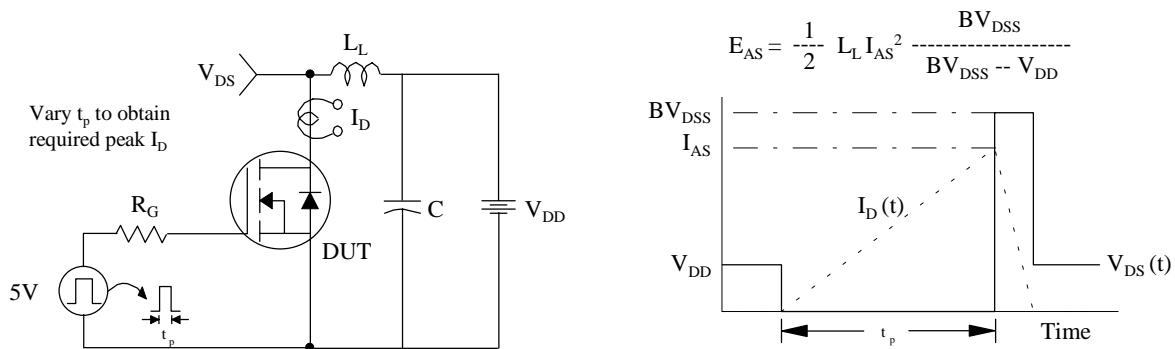


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

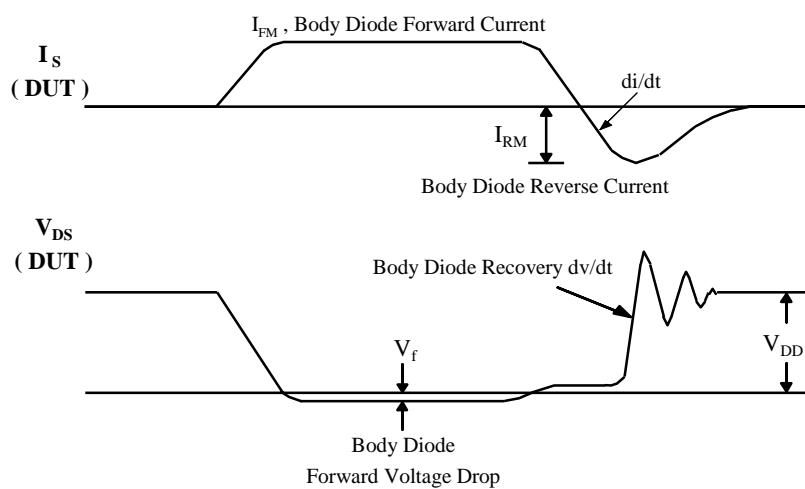
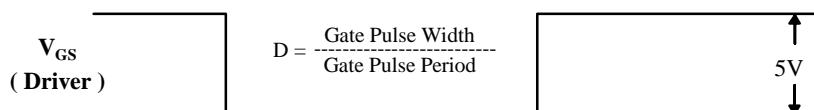
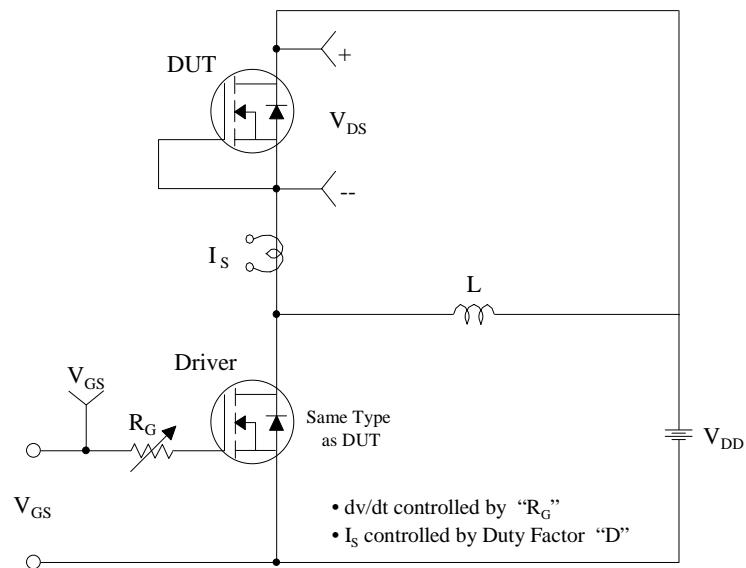


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Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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